

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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Gap Pad® I500R

Thermally Conductive, Reinforced Gap Filling Material

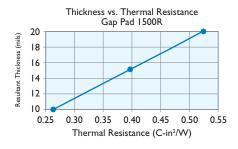
Features and Benefits

- Thermal conductivity: 1.5 W/m-K
- Fiberglass reinforced for puncture, shear and tear resistance
- · Easy release construction
- · Electrically isolating



Gap Pad I500R has the same highly conformable, low-modulus polymer as the standard Gap Pad I500. The fiberglass reinforcement allows for easy material handling and enhances puncture, shear and tear resistance. The natural tack on both sides of the material allows for good compliance to mating surfaces of components, further reducing thermal resistance.

Note: Resultant thickness is defined as the final gap thickness of the application.



TYPICAL PROPERTIES OF GAP PAD 1500R					
PROPERTY	IMPERIAL VALUE	METRIC VALUE		TEST METHOD	
Color	Black	Black		Visual	
Reinforcement Carrier	Fiberglass	Fiberglass		_	
Thickness (inch) / (mm)	0.010 to 0.020	0.254 to 0.508		ASTM D374	
Inherent Surface Tack (1 side)	2	2		_	
Density (Bulk Rubber) (g/cc)	2.1	2.1		ASTM D792	
Heat Capacity (J/g-K)	1.3	1.3		ASTM E1269	
Hardness (Bulk Rubber) (Shore 00) (1)	40	40		ASTM D2240	
Young's Modulus (psi) / (kPa) (2)	45	310		ASTM D575	
Continuous Use Temp (°F) / (°C)	-76 to 392	-60 to 200		_	
ELECTRICAL					
Dielectric Breakdown Voltage (Vac)	>6000	>6000		ASTM D 149	
Dielectric Constant (1000 Hz)	6.0	6.0		ASTM D I 50	
Volume Resistivity (Ohm-meter)	1011	1011		ASTM D257	
Flame Rating	V-O	V-O		U.L. 94	
THERMAL					
Thermal Conductivity (W/m-K)	1.5	1.5		ASTM D5470	
THERMAL PERFORMANCE vs. STRAIN					
	Deflection (% strain)		10	20	30
Thermal Impedance (°C-in²/W) 0.020" (3)			1.07	0.88	0.82
1) Thirty second delay value Shore 00 hardness scale. 2) Young's Modulus, calculated using 0.01 in/min. step rate of strain					

with a sample size of 0.79 inch². 3) The ASTM D5470 test fixture was used. The recorded value includes interfacial thermal resistance. These values are provided for reference only. Actual application performance is directly related to the surface roughness, flatness and pressure applied.

Typical Applications Include:

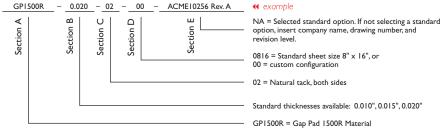
- Telecommunications
- Computer and peripherals
- Power conversion
- RDRAM™ memory modules / chip scale packages
- Areas where heat needs to be transferred to a frame chassis or other type of heat spreader

Configurations Available:

• Sheet form, die-cut parts, and roll form (converted or unconverted)

Building a Part Number

Standard Options



Note: To build a part number, visit our website at www.bergquistcompany.com.



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